

Notice of Allowance dated 4/28/2005

Appl. No. 10/766,390

Amdt. dated May 5 2005

Attorney Docket No. 1217-040068

Amendments to the Specification:

Please replace the paragraph beginning at page 1, line 7, with the following rewritten paragraph:

-- The present invention relates to a film carrier tape for mounting electronic devices thereon capable of correctly giving a defect display (mark) with high precision in a target position on a mounting unit based on a result obtained by a quality inspection such as ~~an visual~~ a visual inspection or an electrical inspection of the film carrier tape (including a TAB (Tape Automated Bonding) tape, a TBGA (Tape Ball Grid Array) tape, a CSP (Chip Size Package) tape, an ASIC (Application Specific Integrated Circuit) tape and a COF (Chip on Film) tape, the film carrier tape having the mark given thereto, and a defect marking method of the film carrier tape. --

Please replace the paragraph beginning at page 4, line 5, with the following rewritten paragraph:

-- As a result of the quality inspection, a defect mark is given to a mounting unit decided determined to be defective. Examples of a marking method of giving a defect mark include a method of forming a punching hole on a defective unit or a method of carrying out ink marking over a defective unit by means of a stamp member. The position of the defect marking is varied for each product. --

Please replace the paragraph beginning at page 6, line 16, with the following rewritten paragraph:

-- As a result of the quality inspection, a defect mark is given to a mounting unit decided determined to be defective ~~and on the~~ and the film carrier tape over which a defect display is carried out is wound upon a reel and is shipped in this condition. --

Please replace the paragraph beginning at page 12, line 2, with the following rewritten paragraph:

-- It is particularly suitable that each invention should be applied to such a type ~~as not to have~~ not having a device hole on a mounting unit. --

Please replace the heading on page 13, line 5, with the following rewritten heading:

DETAILED DESCRIPTION OF THE ~~PREFERRED EMBODIMENTS~~ INVENTION

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Please replace the paragraph beginning at page 15, line 2, with the following rewritten paragraph:

-- More specifically, a manufacturing process such as the formation of a wiring pattern or the like is carried out, and a quality inspection is then performed for a wiring pattern defect on the carrier tape 10 or the like by a human visual inspection or a method of picking up the image of the wiring pattern on the tape by using a CCD camera referred to as a line sensor camera and comparing image pick-up information thus obtained with data on the master pattern of a good product which are prestored, thereby inspecting the defect of the wiring pattern or the like, for example. As a result, a defect mark is given to a mounting unit ~~decided~~ determined to be defective, thereby carrying out a defect display. The defect marking is performed as schematically shown in Fig. 4, for example. Description will be given to an example in which the alignment and punching is carried out by a person using a punching rod 42 of a punching device as marking means. --

Please replace the paragraph beginning at page 21, line 23, with the following rewritten paragraph:

-- In these manners, the defect marking can be carried out in the target position with high precision even if the film carrier tape provided with the target mark does not have the device hole. Consequently, it is particularly suitable that the present invention should be applied to a film carrier tape for mounting electronic devices thereon of such a type ~~as not to have~~ not having the device hole, for example, a COF tape. However, the present invention is not restricted thereto but can also be applied to a film carrier tape for mounting electronic devices thereon of such a type ~~as to have~~ having the device hole. --

Please replace the paragraph beginning at page 23, line 1, with the following rewritten paragraph:

-- According to the film carrier tape in accordance with the present invention, moreover, a plurality of mounting units ~~decided~~ determined to be defective at the quality inspecting step has the final defect marking carried out with high precision in the target position based on the target mark. Therefore, it is possible to reduce an error of defect recognition caused by the shift of the defect mark in IC mounting or the like.--